



# RHBS810

Glass Passivated Single-Phase 8.0Amp Surface Mount Bridge Rectifier

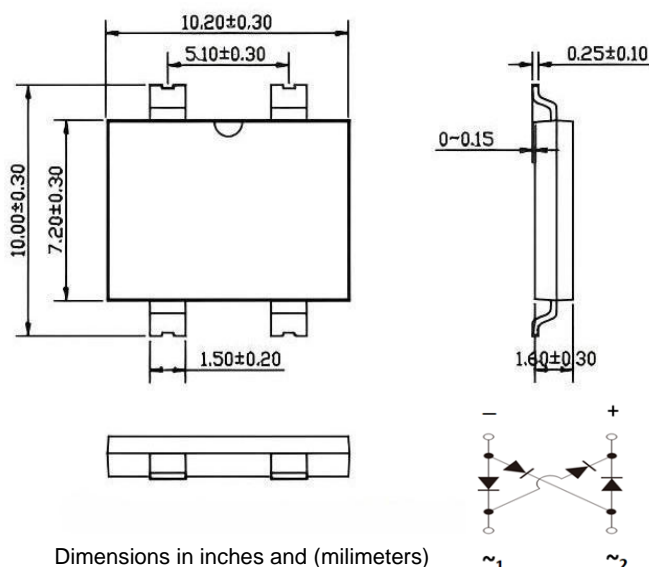
## Features

- Surface mount bridge, small package;
- Ideal for printed circuit boards;
- Glass passivated chip junction;
- High forward current capability up to 8.0A;
- High surge current capability;
- High heat dissipation capability;
- Low profile package;
- Low forward voltage drop;
- Plastic package has Underwrites Laboratory Flammability Classification 94V-0;

## Mechanical Data

- Case: HBS;
- Epoxy meets UL-94V-0 Flammability rating;
- Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102;
- High temperature soldering guaranteed:  
Solder Reflow 260°C, 10seconds;
- Polarity: As marked on body;
- Marking: Type number;

Case: HBS



Dimensions in inches and (millimeters)

## Typical Applications

General purpose use in AC-to-DC bridge full wave rectification for Fast Charging, Switching Power Supply, USB PD, Adapter and 3-in-1 Power Board, etc.

## Maximum Ratings and Electrical Characteristics

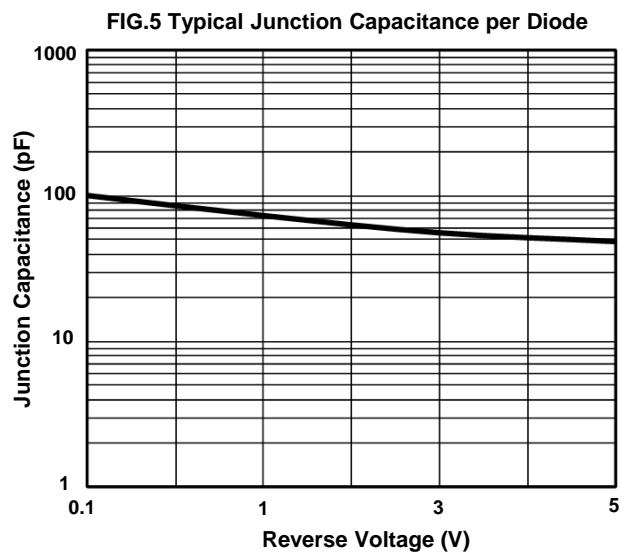
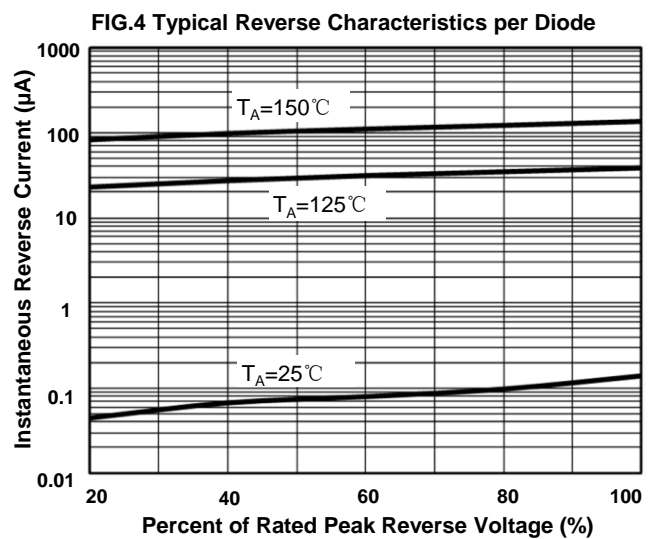
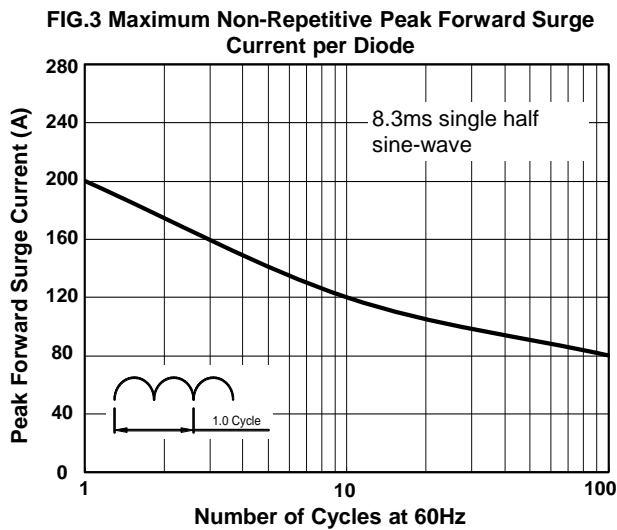
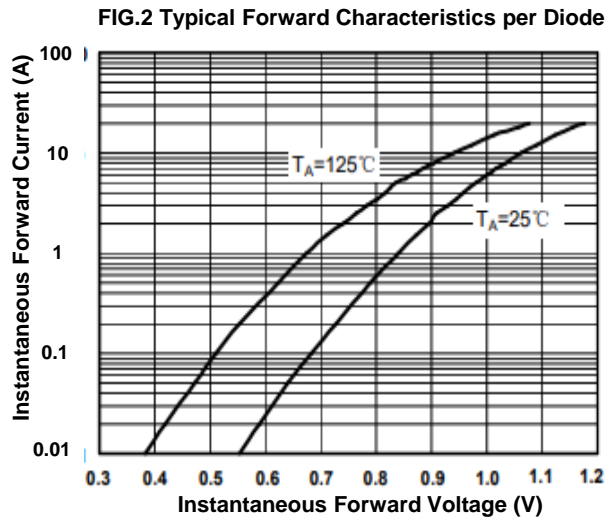
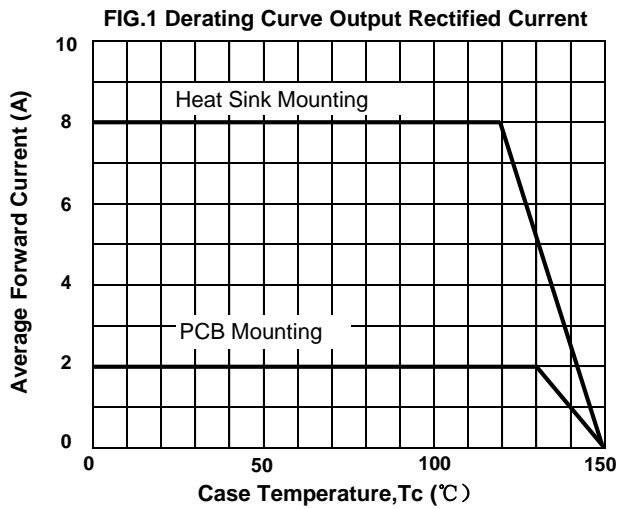
Ratings at 25°C ambient temperature unless otherwise specified. Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Parameter	Symbol	RHBS810	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	1000	V
Maximum RMS voltage	$V_{RMS}$	700	V
Maximum DC blocking voltage	$V_{DC}$	1000	V
Maximum average forward rectified output current at $T_A=25^\circ\text{C}$	$I_{F(AV)}$	8.0	Amps
Non-Repetitive Peak forward surge current 8.3 ms single sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	200	Amps
Rating for fusing ( $t<8.3\text{ms}$ )	$I^2t$	166	$\text{A}^2\text{sec}$
Instantaneous forward voltage drop per diode @ $I_F=1.0\text{A}$ @ $I_F=4.0\text{A}$ @ $I_F=8.0\text{A}$	$V_F$	0.95 max. 1.1 max. 1.3max.	Volt
Reverse Current at Rated DC Blocking Voltage $T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	$I_R$	0.20 Typ. 5.0 max 50 Typ. 100 max.	$\mu\text{A}$
Maximum reverse recovery time ( $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$ )	$T_{rr}$	350	nS
Typical thermal resistance	$R_{\theta J-A}$ $R_{\theta J-C}$ $R_{\theta J-L}$	70.0 15.0 22.0	$^\circ\text{C/W}$
Operating junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

Note1: Measured at 1.0MHz and applied reverse voltage of 5.0V DC;

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Suggested PCB printfoot layout

